

## CLAIMS AS AMENDED

Sub 1  
A1  
1. A laser sintering method, comprising providing a material including individual particles on a substrate, completely sintering the individual particles within the material together on the substrate and enhancing adhesion of the material on the substrate without damaging the substrate.

A2  
6. The method of claim 5, wherein the controlling further comprises stopping enhancement of the adhesion by causing a temperature difference between the substrate and the material such that a temperature gradient stops the enhancement of the adhesion.

A3  
11. The method of claim 10, further comprising obtaining peak power in gigawatts with low energy per pulse and with short pulses.

A4  
24. The method of claim 23, wherein the feedback control system is a pyrometer.

25. The method of claim 24, further comprising providing an output of the pyrometer to a computing device.